

SAN DIEGO, CA – December 17 – Chiplet Summit Features the Latest Chip Design Technology

Chiplet Summit's 2025 event offers the last word on leading-edge chip design at the Santa Clara Convention Center on January 21-23. The Tuesday tutorials cover advanced packaging technologies, die-to-die interfaces, design methods, working with foundries, and the Open Chiplet Economy. Wednesday sessions cover creating foundry-ready designs, getting the most from high-bandwidth memory (HBM), and system-technology co-optimization (STCO). Thursday panels discuss viable markets, making money with chiplets, and long-term trends.

The Summit also offers major company keynotes, expert tables, an annual update of technology and markets, and coverage of chiplet-based design from disaggregation through manufacturing. An exhibit hall has key products from industry leaders such as Synopsys, Alphawave IP, Cadence, Keysight, Achronix, Primesas, Deca Technologies, and Siemens.

"Chiplet Summit will help designers get all the information they need to create leading-edge devices," said Chuck Sobey, Summit General Chair. "We invite everyone across the ecosystem to come learn about new technologies, discuss issues face-to-face, and set the direction for the industry."

To discuss exhibiting, contact:

Elizabeth Leventhal, Exhibit Sales Director
Elizabeth@ChipletSummit.com
+1.760.809.5755

About Chiplet Summit

Chiplet Summit, produced by Semper Technologies, showcases the mainstream applications, key technologies, and leading vendors that are driving the rapidly expanding chiplet market.

Media Contact

Elizabeth Leventhal
+1.760.809.5755
Press@ChipletSummit.com